

#### **Features**

- High isolation 5000 VRMS
- Supports 0.3 A, 0.6 A, 0.9 A and 1.2 A
- RoHS compliant
- REACH compliance
- External creepage > 7.5mm
- Internal creepage > 6.0mm
- Insulation distance > 0.4mm
- Regulatory Approvals
  - UL UL1577 (pending approval)
  - VDE EN60747-5-5(VDE0884-5)
  - CQC GB4943.1, GB8898
  - IEC60065, IEC60950

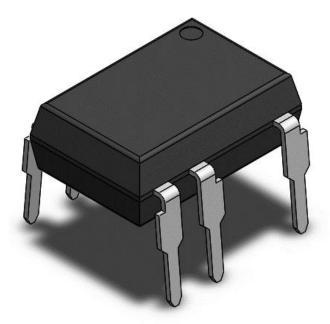
#### **Description**

The zero crossing power Triac consists of a Triac and a photo-Triac, which is optically coupled to a gallium arsenide Infrared emitting diode, and house in a 7-lead DIP package. It also comes with different lead forming options.

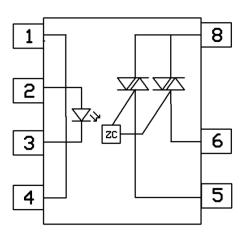
### **Applications**

- Home appliances
- Industrial equipment

### **Package Outline**



#### **Schematic**



Note: Different bending options available. See package dimension.



### Absolute Maximum Rating at 25°C

Symbol	Parameters		Ratings	Units	Notes
Viso	Isolation voltage		5000	Vrms	
T <sub>OPR</sub>	Operating temp	perature	-40 ~+85	°C	
T <sub>STG</sub>	Storage temp	erature	-40 ~+125	°C	
_	Soldering temp	perature	260	°C	
TsoL	Wave soldering to	emperature	260	°C	
Emitter			•	<u> </u>	
lF	LED forward	current	50	mA	
V <sub>R</sub>	LED reverse	voltage	6	V	
I <sub>FP</sub>	Peak forward	1			
Pin	Power dissipation		75 mW		
Detector			•	<u> </u>	
V <sub>DRM</sub>	Repetitive peak OFF	600	V		
		CTT02XX	0.3		
	S) Continuous Current Load	CTT12XX	0.6		
I <sub>T(RMS)</sub>		CTT22XX	0.9	A	
		CTT32XX	1.2		
		CTT02XX	3		
Ітѕм	Peak Current Load	CTT12XX	6		
		CTT22XX	9	A	
		CTT32XX	12		
Pout	Power dissipation		800	mW	
PT	Total power dissipation		850	mW	



### **Electrical Characteristics** $T_A = 25$ °C (unless otherwise specified)

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I <sub>F</sub> =10mA	-	-	1.3	V	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 6V	-	-	5	μΑ	
C <sub>IN</sub>	Input Capacitance	f= 1MHz	-	45	-	pF	

#### **Detector Characteristics**

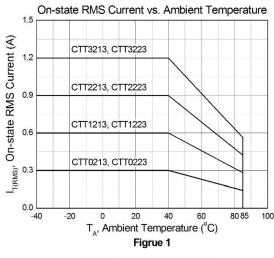
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I <sub>DRM1</sub>	Peak Blocking Current	I <sub>F</sub> = 0mA, V <sub>DRM</sub> = 600V	-	-	100	uA	
I <sub>DRM2</sub>	Inhibit Leakage Current	I <sub>F</sub> = = Rated I <sub>FT</sub> , V <sub>DRM</sub> = 600V			500	uA	
$V_{INH}$	Inhibit Voltage	I <sub>F</sub> = Rated I <sub>FT</sub>	-	-	50	V	
$V_{TM}$	Peak On-State Voltage	I <sub>F</sub> = Rated I <sub>FT</sub> , I <sub>TM</sub> = 100mA	-	-	2.5	V	
al. //al4	Critical Rate of Rise off-State	V Detect V	200			\// -	
dv/dt	Voltage V <sub>PEAK</sub> = Rated V <sub>DRM</sub>	200	-	-	V/μs		

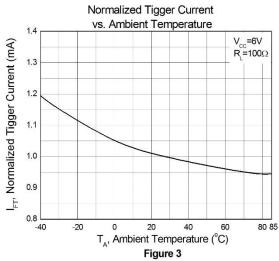
#### **Transfer Characteristics**

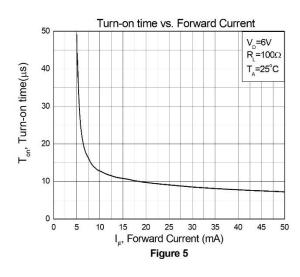
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I <sub>FT</sub>	Input Trigger Current	Terminal Voltage = 3V	-	•	10	mA	
lн	Holding Current		-	-	25	mA	
Rıo	Isolation Resistance	Vio= 500VDC	1x10 <sup>11</sup>		-	Ω	
C <sub>IO</sub>	Isolation Capacitance	f= 1MHz	-	0.25	-	pF	

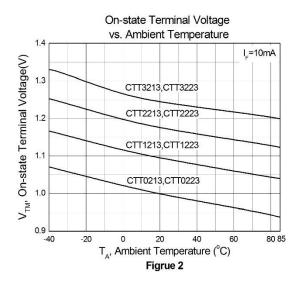


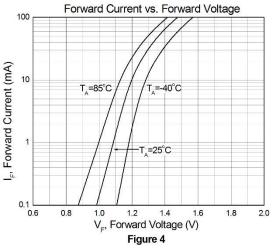
#### **Typical Characteristic Curves**

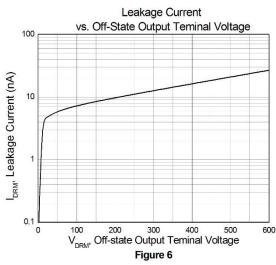




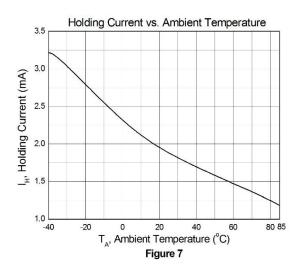


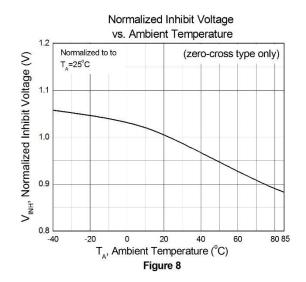








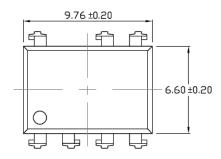


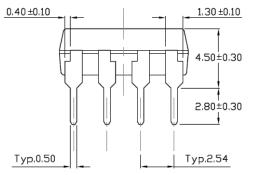


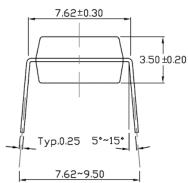


#### Package Dimension Dimensions in mm unless otherwise stated

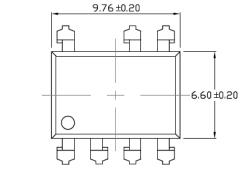
### Standard DIP - Through Hole

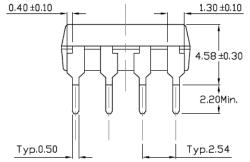


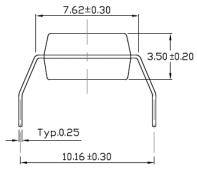




#### **Gullwing (400mil) Lead Forming – Through Hole (M Type)**

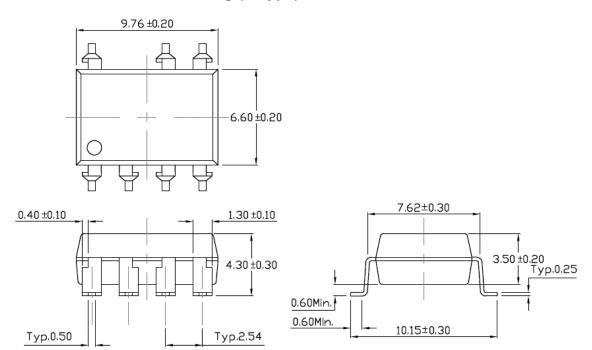




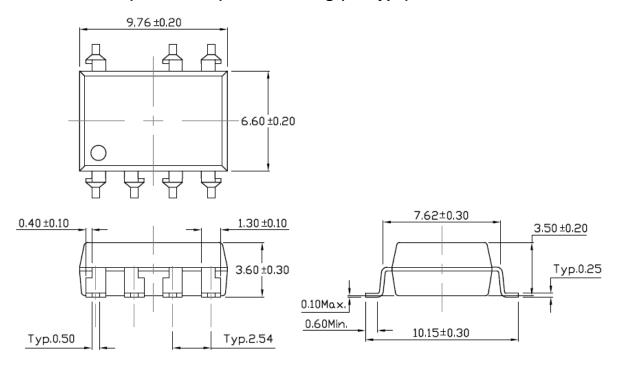




#### **Surface Mount Lead Forming (S Type)**

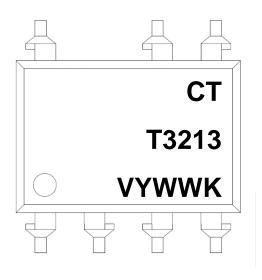


### **Surface Mount (Low Profile) Lead Forming (SL Type)**





#### **Device Marking**



#### Note:

CT : Denotes "CT Micro" T3213 : Product Number

V

: VDE Safety Mark (option) Υ : Fiscal Year

WW : Work Week

Κ : Production Code

### **Ordering Information**

### CTTX213(V)(Y)(Z)

= Denotes "CT Micro" CT

TX213 = Product Number (Current Rating Option X=0, 1, 2, or 3)

٧ = VDE safety mark option (V, or none) Υ = Lead form option (S, SL, M or none) Ζ = Tape and reel option (T1, T2 or none)

Option	Description	Quantity
None	Standard 8 Pin Dip	40 Units/Tube
М	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping	1000 Units/Reel

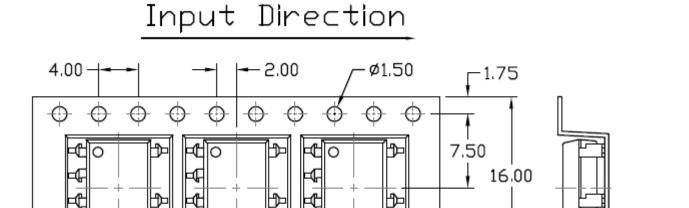


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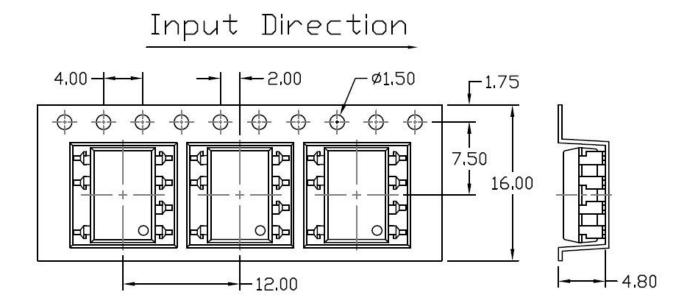
### Carrier Tape Specifications Dimensions in mm unless otherwise stated

-12.00

### Option S(T1) & SL(T1)



#### Option S(T2) & SL(T2)





#### Wave soldering (JEDEC22A111 compliant)

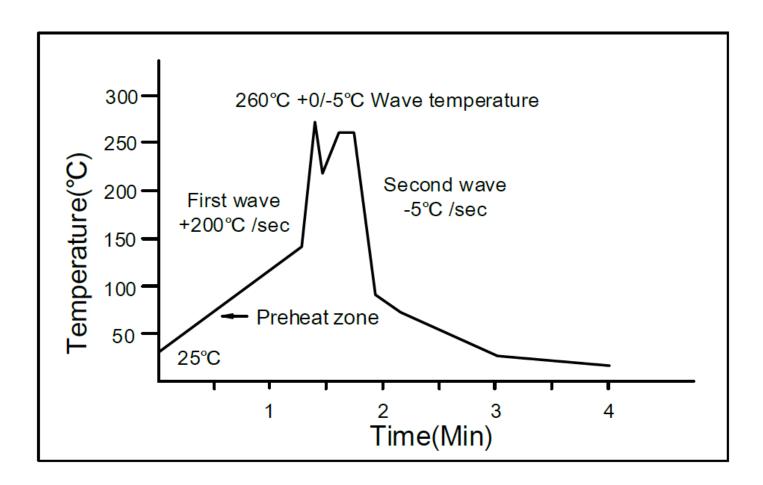
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



### Hand soldering by soldering iron

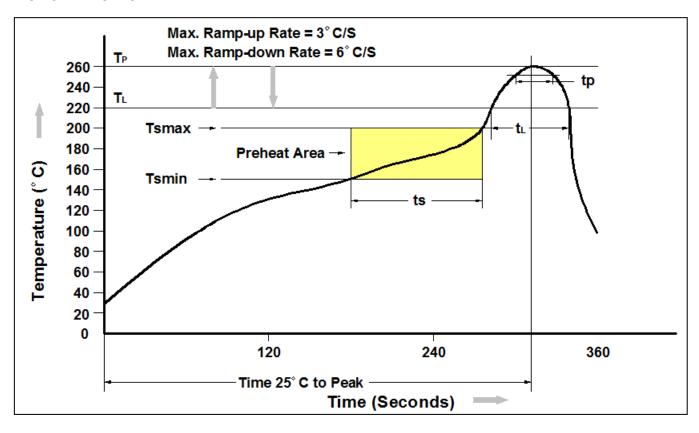
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350+0/-5°C

Time: 3 sec max.



#### **Reflow Profile**



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t₂)	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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